ABSTRACT

A circuit board includes a plurality of through holes (14, 44) into which a plurality of leads (18) of one electronic devices are inserted and soldered. Among these through holes (14, 44), the volume of through hole (14b, 24b, 34b, 44b, 54, 64b) into which the outermost end lead of leads (18) of the electronic device is inserted, is set greater than the volume of through hole (14a, 44a), into which the lead at the position nearest to the center of the electronic device is inserted. Alternatively, the size of through hole (14b, 24b, 34b, 44b, 54, 64b), into which the outermost end lead of leads (18) is inserted, the size being measured in a direction of a straight line that connects a position of the outermost end lead of leads (18) of the electronic device, which is mounted before being soldered, and a center position of the electronic device at the time when the electronic device is mounted, is larger than the size of through hole (14a, 44a), into which the lead of leads (18) which is located at the position nearest to the center of the electronic device is inserted, the size being measured in any direction in a plane. Alternatively, the center position of through hole (74b), into which outermost end lead (18) of the electronic device is inserted, is shifted in a direction away from or approaching the center position of the electronic device at the time when the electronic device is mounted, from the position of outermost end lead (18) of the electronic device, which is mounted before being soldered, in accordance with the relationship between the amount of thermal expansion of the electronic device and that of the circuit board.